



DXTP03200BP5

200V PNP HIGH VOLTAGE TRANSISTOR PowerDI5

Features

- $BV_{CEO} = -200V$
- I_C = -2A High Continuous Collector Current
- I_{CM} = -5A Peak Collector Current
- P_D up to 3.2W
- 43% smaller than SOT223; 60% smaller than TO252 (DPAK)
- Maximum height just 1.1mm
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Application

- DC DC Conversion
- **Telecoms**
- Power Management

Mechanical Data

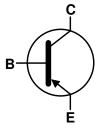
- Case: PowerDI®5
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.093 grams (Approximate)



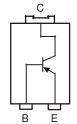




Bottom View



Device Schematic



Pin-Out Diagram

Ordering Information (Note 4)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DXTP03200BP5-13	AEC-Q101	DTP3200B	13	16	5.000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



DTP3200B = Product Type Marking Code Oll = Manufacturers' Code Marking K = Factory Designator YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 09 for 2009) WW = Week Code (01 to 53)



Absolute Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-220	V
Collector-Emitter Voltage	V_{CEO}	-200	V
Emitter-Base Voltage	V_{EBO}	-7	V
Continuous Collector Current	I _C	-2	A
Base Current	I _B	-1	Α
Peak Pulse Current	I _{CM}	-5	A

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	3.2	W
Thermal Resistance, Junction to Ambient Air (Note 5)	$R_{ hetaJA}$	39	°C/W
Power Dissipation (Note 6)	P _D	1.7	W
Thermal Resistance, Junction to Ambient Air (Note 6)	$R_{ hetaJA}$	75	°C/W
Power Dissipation (Note 7)	P _D	0.74	W
Thermal Resistance, Junction to Ambient Air (Note 7)	$R_{ heta JA}$	169	°C/W
Thermal Resistance, Junction to Lead (Note 8)	$R_{ heta JL}$	5.6	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

ESD Ratings (Note 9)

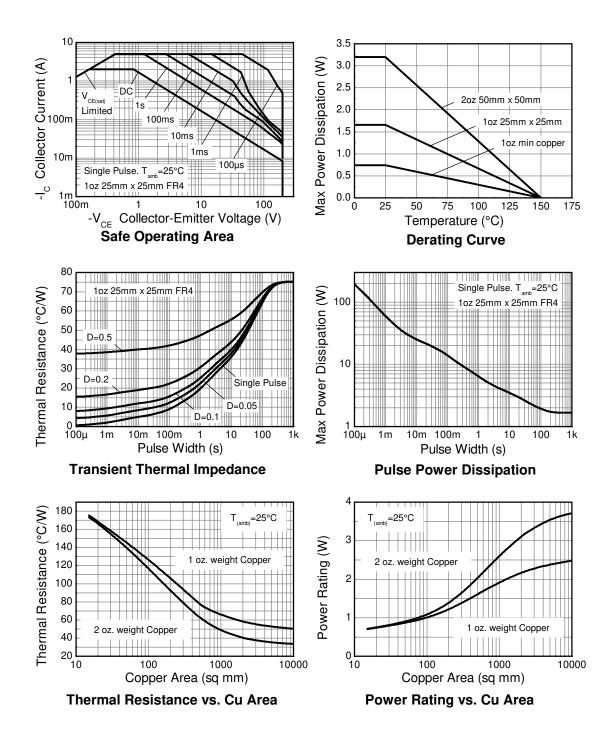
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

Notes:

- 5. Device mounted on FR-4 PCB, single sided 2 oz. copper, collector pad dimensions 50mm x 50mm.
 6. Device mounted on FR-4 PCB, single sided 1 oz. copper, collector pad dimensions 25mm x 25mm.
 7. Device mounted on FR-4 PCB, single sided 1 oz. copper, minimum recommended pad layout.
 8 Thermal resistance from junction to solder-point (on the exposed collector pad).
 9. Refer to JEDEC specification JESD22-A114 and JESD22-A115.



Thermal Characteristics and Derating Information





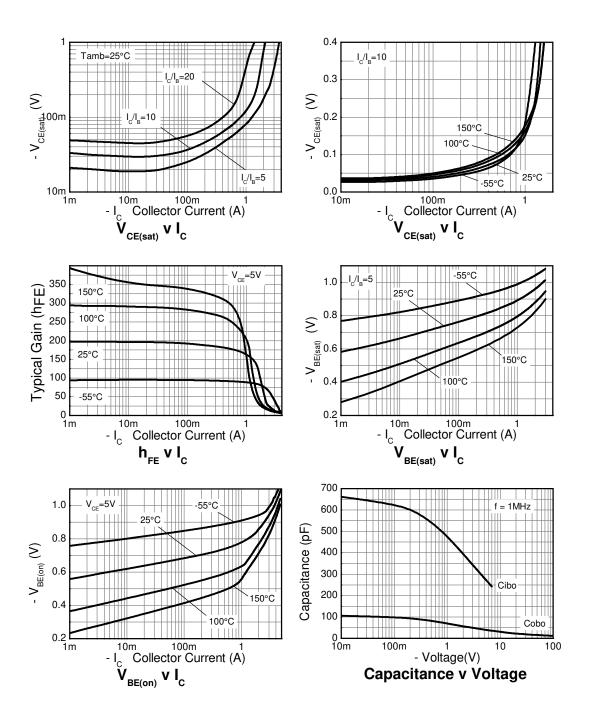
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	V _{(BR)CBO}	-220	-245	_	V	$I_{C} = -100 \mu A$
Collector-Emitter Breakdown Voltage (Note 10)	V _{(BR)CEO}	-200	-225	_	V	$I_C = -10mA$
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	-7	-8.4	_	V	$I_E = -100\mu A$
Collector Cutoff Current	I _{CBO}	-	<1 -	-50 -0.5	nA μA	$V_{CB} = -200V$ $V_{CB} = -200V$, $T_{A} = +100^{\circ}C$
Emitter Cutoff Current	I _{EBO}	-	<1	-10	nA	V _{EB} = -6V
Collector-Emitter Saturation Voltage (Note 10)	V _{CE(sat)}	- - -	-37 -130 -135 -180	-50 -155 -160 -275	mV	$I_C = -0.1A$, $I_B = -10mA$ $I_C = -0.5A$, $I_B = -25mA$ $I_C = -1A$, $I_B = -100mA$ $I_C = -2A$, $I_B = -400mA$
Base-Emitter Saturation Voltage (Note 10)	V _{BE(sat)}	=	-955	-1,100	mV	I _C = -2A, I _B = -400mA
Base-Emitter Turn-On Voltage (Note 10)	V _{BE(on)}	_	-860	-1,000	mV	$V_{CE} = -5V, I_{C} = -2A$
DC Current Gain (Note 10)	h _{FE}	100 100 20	195 170 50 5	300 - -	I	$V_{CE} = -5V, I_C = -10mA$ $V_{CE} = -5V, I_C = -1A$ $V_{CE} = -5V, I_C = -2A$ $V_{CE} = -5V, I_C = -5A$
Transition Frequency	f _T	-	105	-	MHz	$V_{CE} = -10V$, $I_{C} = -100$ mA, $f = 50$ MHz
Output Capacitance	C _{obo}	-	31	_	рF	V _{CB} = -10V, f = 1MHz
Delay Time	t _d	-	21	-	ns	
Rise Time	t _r	=	18	=	ns	$V_{CC} = -50V, I_{C} = -1A,$
Storage Time	ts	-	680	-	ns	$I_{B1} = -I_{B2} = -100 \text{mA}$
Fall Time	t _f	-	75		ns	

Note: 10. Pulse Test: Pulse width \leq 300 μ s. Duty cycle \leq 2.0%.



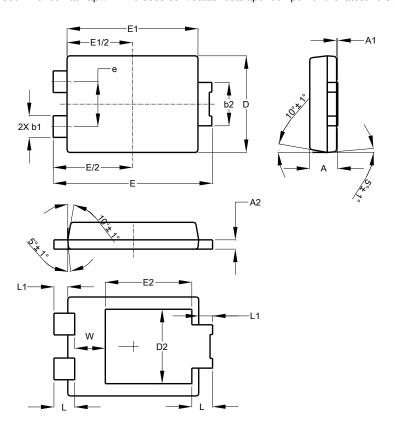
Typical Characteristics





Package Outline Dimensions

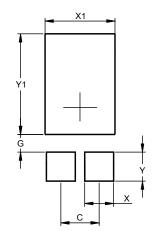
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



POWERDI [®] 5					
Dim	Min	Max	Тур		
Α	1.05	1.15	1.10		
A 1	0.00	0.05			
A2	0.33	0.43	0.381		
b1	0.80	0.99	0.89		
b2	1.70	1.88	1.78		
D	3.90	4.05	3.966		
D2			3.054		
Е	6.40	6.60	6.504		
е			1.84		
E1	5.30	5.45	5.37		
E2			3.549		
L	0.75	0.95	0.85		
L1	0.50	0.65	0.57		
W	1.10	1.41	1.255		
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)				
С	1.840				
G	0.852				
X	1.390				
X1	3.360				
Υ	1.400				
Y1	4.860				

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



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